

4V Drive Nch+Pch MOSFET

SP8M10FRA

●Structure

Silicon N-channel / P-channel MOSFET

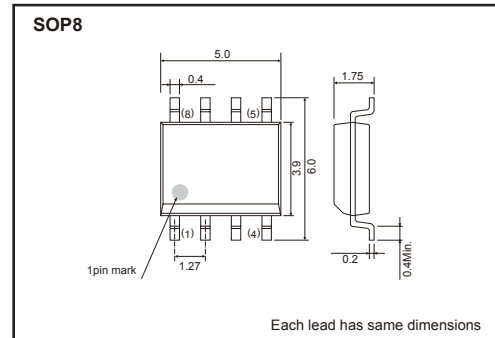
●Features

- 1) Low on-resistance.
- 2) Built-in G-S Protection Diode.
- 3) Small Surface Mount Package (SOP8).

●Application

Power switching, DC / DC converter.

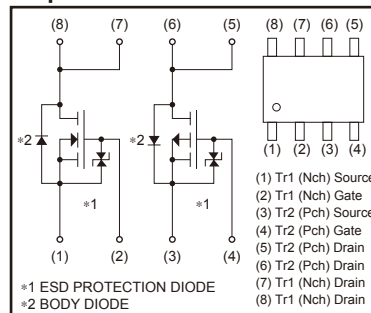
●Dimensions (Unit : mm)



●Packaging specifications

| Type | Package | Taping |
|-----------|------------------------------|--------|
| | Code | TB |
| | Basic ordering unit (pieces) | 2500 |
| SP8M10FRA | | ○ |

●Equivalent circuit



*A protection diode is included between the gate and the source terminals to protect the diode against static electricity when the product is in use. Use the protection circuit when the fixed voltages are exceeded.

●Absolute maximum ratings (Ta=25°C)

| Parameter | Symbol | Limits | | Unit | |
|-----------------------------|-------------------|--------------------|----------|------|---|
| | | Nchannel | Pchannel | | |
| Drain-source voltage | V _{DSS} | 30 | -30 | V | |
| Gate-source voltage | V _{GSS} | ±20 | ±20 | V | |
| Drain current | Continuous | I _D | ±7.0 | ±4.5 | A |
| | Pulsed | I _{DP} *1 | ±28 | ±18 | A |
| Source current (Body diode) | Continuous | I _S | 1.6 | -1.6 | A |
| | Pulsed | I _{SP} *1 | 28 | -18 | A |
| Total power dissipation | P _D *2 | 2 | | W | |
| Channel temperature | T _{ch} | 150 | | °C | |
| Storage temperature | T _{stg} | -55 to +150 | | °C | |

*1 Pw≤10μs, Duty cycle≤1%
*2 MOUNTED ON A CERAMIC BOARD.

●Thermal resistance

| Parameter | Symbol | Limits | Unit |
|--------------------|--------------------------|--------|--------|
| Channel to ambient | R _{th (ch-a)} * | 62.5 | °C / W |

*MOUNTED ON A CERAMIC BOARD.

Transistors

N-ch

●Electrical characteristics (Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|---|-----------------------|------|------|------|------|---|
| Gate-source leakage | I _{GSS} | – | – | ±10 | μA | V _{GS} =±20V, V _{DS} =0V |
| Drain-source breakdown voltage | V _{(BR) DSS} | 30 | – | – | V | I _D =1mA, V _{GS} =0V |
| Zero gate voltage drain current | I _{DSS} | – | – | 1 | μA | V _{DS} =30V, V _{GS} =0V |
| Gate threshold voltage | V _{GS(th)} | 1.0 | – | 2.5 | V | V _{DS} =10V, I _D =1mA |
| Static drain-source on-state resistance | R _{DS(on)} * | – | 17 | 25 | mΩ | I _D =7.0A, V _{GS} =10V |
| | | – | 23 | 35 | | I _D =7.0A, V _{GS} =4.5V |
| | | – | 25 | 37 | | I _D =7.0A, V _{GS} =4V |
| Forward transfer admittance | Y _{fs} * | 5.0 | – | – | S | I _D =7.0A, V _{DS} =10V |
| Input capacitance | C _{iss} | – | 600 | – | pF | V _{DS} =10V |
| Output capacitance | C _{oss} | – | 200 | – | pF | V _{GS} =0V |
| Reverse transfer capacitance | C _{rss} | – | 120 | – | pF | f=1MHz |
| Turn-on delay time | t _{d(on)} * | – | 8 | – | ns | I _D =3.5A, V _{DD} ≐15V |
| Rise time | t _r * | – | 10 | – | ns | V _{GS} =10V |
| Turn-off delay time | t _{d(off)} * | – | 37 | – | ns | R _L =4.29Ω |
| Fall time | t _f * | – | 11 | – | ns | R _G =10Ω |
| Total gate charge | Q _g * | – | 8.4 | – | nC | V _{DD} ≐15V |
| Gate-source charge | Q _{gs} * | – | 1.9 | – | nC | V _{GS} =5V |
| Gate-drain charge | Q _{gd} * | – | 3.3 | – | nC | I _D =7.0A |

*Pulsed

●Body diode characteristics (Source-Drain) (Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|-----------------|-------------------|------|------|------|------|---|
| Forward voltage | V _{SD} * | – | – | 1.2 | V | I _S =6.4A, V _{GS} =0V |

*Pulsed

Transistors

P-ch

●Electrical characteristics (Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|---|-----------------------|------|------|------|------|---|
| Gate-source leakage | I _{GSS} | – | – | ±10 | μA | V _{GS} = ±20V, V _{DS} =0V |
| Drain-source breakdown voltage | V _{(BR) DSS} | –30 | – | – | V | I _D = –1mA, V _{GS} =0V |
| Zero gate voltage drain current | I _{DSS} | – | – | –1 | μA | V _{DS} = –30V, V _{GS} =0V |
| Gate threshold voltage | V _{GS(th)} | –1.0 | – | –2.5 | V | V _{DS} = –10V, I _D = –1mA |
| Static drain-source on-state resistance | R _{DS(on)} * | – | 40 | 56 | mΩ | I _D = –4.5A, V _{GS} = –10V |
| | | – | 57 | 80 | | I _D = –2.5A, V _{GS} = –4.5V |
| | | – | 65 | 90 | | I _D = –2.5A, V _{GS} = –4.0V |
| Forward transfer admittance | Y _{fs} * | 3.5 | – | – | S | I _D = –2.5A, V _{DS} = –10V |
| Input capacitance | C _{iss} | – | 850 | – | pF | V _{DS} = –10V |
| Output capacitance | C _{oss} | – | 190 | – | pF | V _{GS} =0V |
| Reverse transfer capacitance | C _{rss} | – | 120 | – | pF | f=1MHz |
| Turn-on delay time | t _{d(on)} * | – | 10 | – | ns | I _D = –2.5A, V _{DD} ≐ –15V |
| Rise time | t _r * | – | 25 | – | ns | V _{GS} = –10V |
| Turn-off delay time | t _{d(off)} * | – | 60 | – | ns | R _L =6.0Ω |
| Fall time | t _f * | – | 25 | – | ns | R _G =10Ω |
| Total gate charge | Q _g * | – | 8.5 | – | nC | V _{DD} ≐ –15V |
| Gate-source charge | Q _{gs} * | – | 2.5 | – | nC | V _{GS} = –5V |
| Gate-drain charge | Q _{gd} * | – | 3.0 | – | nC | I _D = –4.5A |

*Pulsed

●Body diode characteristics (Source-Drain) (Ta=25°C)

| Parameter | Symbol | Min. | Typ. | Max. | Unit | Conditions |
|-----------------|-----------------|------|------|------|------|--|
| Forward voltage | V _{SD} | – | – | –1.2 | V | I _S =–1.6A, V _{GS} =0V |

Transistors

N-ch

●Electrical characteristic curves

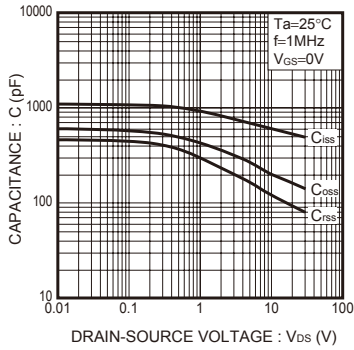


Fig.1 Typical Capacitance vs. Drain-Source Voltage

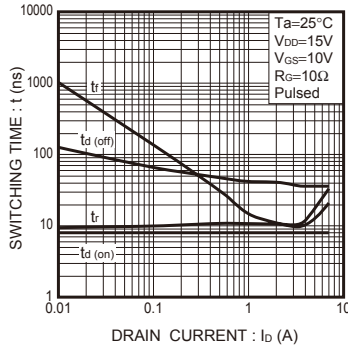


Fig.2 Switching Characteristics

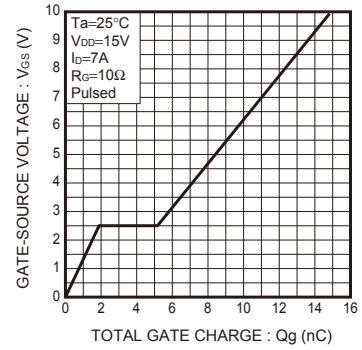


Fig.3 Dynamic Input Characteristics

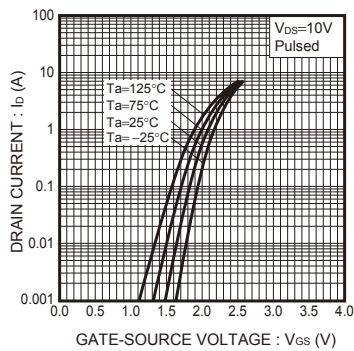


Fig.4 Typical Transfer Characteristics

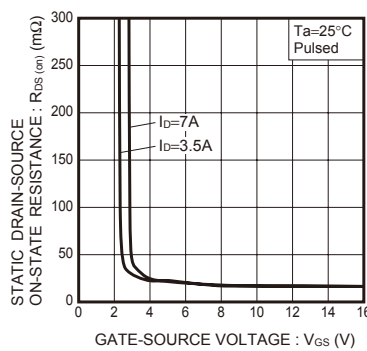


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

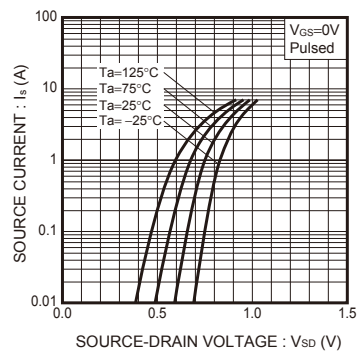


Fig.6 Source Current vs. Source-Drain Voltage

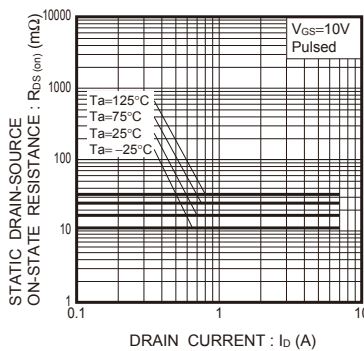


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (I)

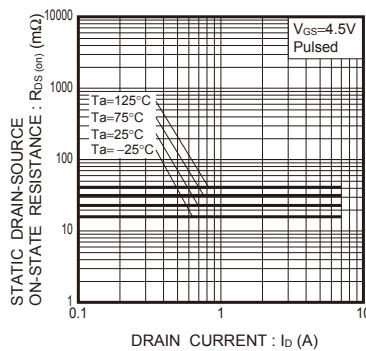


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (II)

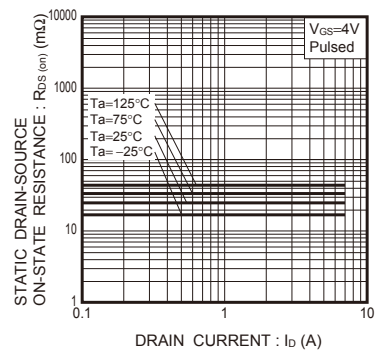


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current (III)

Transistors

P-ch

●Electrical characteristic curves

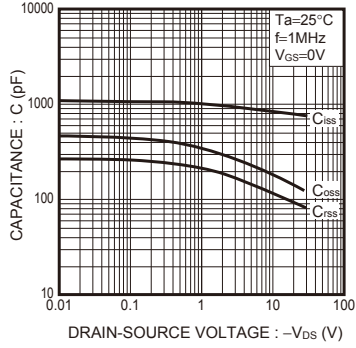


Fig.1 Typical Capacitance vs. Drain-Source Voltage

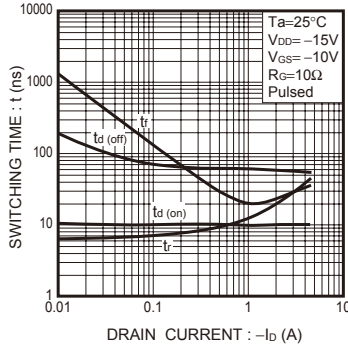


Fig.2 Switching Characteristics

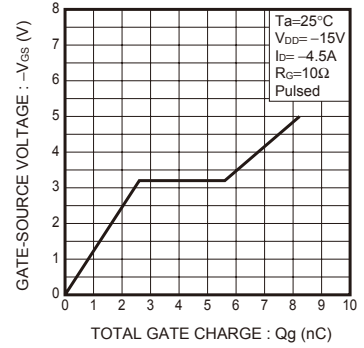


Fig.3 Dynamic Input Characteristics

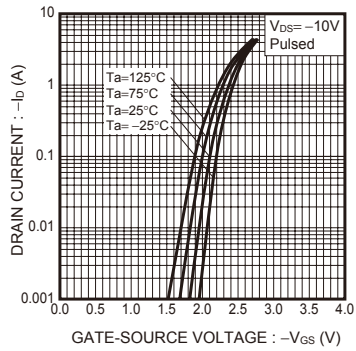


Fig.4 Typical Transfer Characteristics

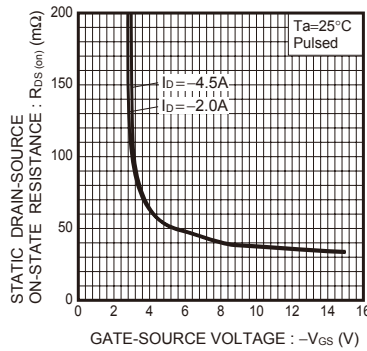


Fig.5 Static Drain-Source On-State Resistance vs. Gate-Source Voltage

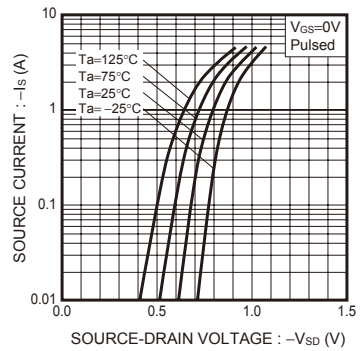


Fig.6 Source Current vs. Source-Drain Voltage

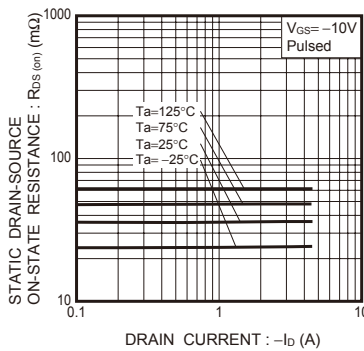


Fig.7 Static Drain-Source On-State Resistance vs. Drain Current (I)

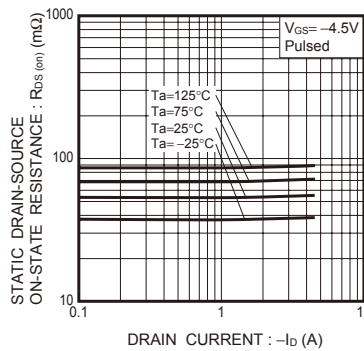


Fig.8 Static Drain-Source On-State Resistance vs. Drain Current (II)

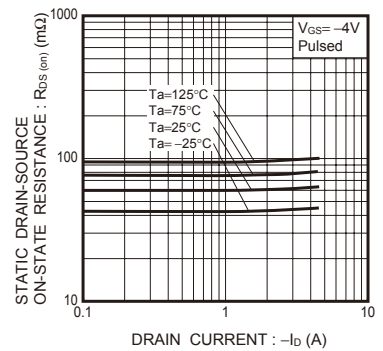


Fig.9 Static Drain-Source On-State Resistance vs. Drain Current (III)

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| JAPAN | USA | EU | CHINA |
|-----------|-----------|------------|-----------|
| CLASS III | CLASS III | CLASS II b | CLASS III |
| CLASS IV | | CLASS III | |

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 - [b] Installation of redundant circuits to reduce the impact of single or multiple circuit failure
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 - [f] Sealing or coating our Products with resin or other coating materials
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 - [h] Use of the Products in places subject to dew condensation
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of Ionizer, friction prevention and temperature / humidity control).

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 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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SP8M10FRA - Web Page

| | |
|-----------------------------|-----------|
| Part Number | SP8M10FRA |
| Package | SOP8 |
| Unit Quantity | 2500 |
| Minimum Package Quantity | 2500 |
| Packing Type | Taping |
| Constitution Materials List | inquiry |
| RoHS | Yes |